

## ABSTRACT OF THE DISCLOSURE

As means for solving a problem of a positional shift of a land and a hole which is caused by an alignment in the formation of an etching resist layer and a plated resist layer in a method of manufacturing a circuit board, there are provided a method of manufacturing a circuit board including the steps of forming a first resin layer on a surface of an insulating substrate having a conductive layer on the surface and an internal wall of a through hole or/and a non-through hole, forming a second resin layer which is insoluble or slightly soluble in a developing solution for the first resin layer on the first resin layer provided on the surface conductive layer, and removing the first resin layer provided over the hole with the developing solution for the first resin layer, and a method of manufacturing a circuit board including the step of uniformly charging a surface of the first resin layer to induce a potential difference to the first resin layer provided over the hole and the first resin layer provided on the surface conductive layer before forming the second resin layer. Moreover, there is provided a circuit board having a hole with a small positional shift and high precision.